







APGF1012GBRC-07

1 x 1 x 0.25 mm Full-Color Surface Mount LED

DESCRIPTIONS

- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- The Blue source color devices are made with InGaN Light Emitting Diode
- The Hyper-Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 1.0 mm x 1.0 mm SMD LED, 0.25 mm thickness
- · Low power consumption
- Package: 4000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- · RoHS compliant

APPLICATIONS

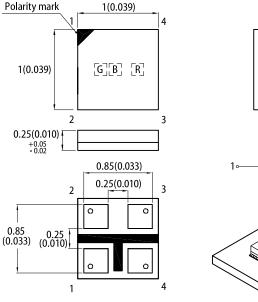
- Backlight
- · Status indicator
- Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

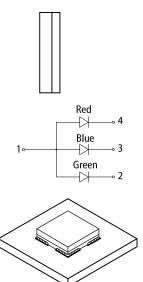
ATTENTION

Observe precautions for handling Electrostatic discharge sensitive devices

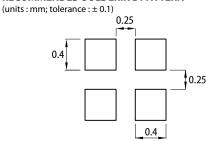


PACKAGE DIMENSIONS





RECOMMENDED SOLDERING PATTERN



Mask open area ratio: 80% Mask thickness: 80~100um

- 1. All dimensions are in millimeters (inches).
- Tolerance is ±0.1(0.004") unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

 The device has a single mounting surface. The device must be mounted according to the specifications

SELECTION GUIDE

Part Number	Emitting Color	Lana Tyra	Iv (mcd) @ 5mA [2]		Viewing Angle [1]
Part Number	(Material)	Lens Type	Min.	Тур.	201/2
APGF1012GBRC-07	■ Green (InGaN)	Water Clear	80	220	
	■ Blue (InGaN)		10	23	150°
	■ Hyper Red (AlGaInP)		15	30	

- Notes.
 1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous flux: +/-15%.
- 3. Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Comple of	Fusittina Calan	Va	Value	
Parameter	Symbol	Emitting Color	Тур.	Max. Unit	
Wavelength at Peak Emission I _F = 5mA	λ_{peak}	Green Blue Hyper Red	515 460 632	-	nm
Dominant Wavelength I _F = 5mA	λ _{dom} ^[1]	Green Blue Hyper Red	525 465 624	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 5mA	Δλ	Green Blue Hyper Red	30 25 20	-	nm
Capacitance	С	Green Blue Hyper Red	45 100 25	-	pF
Forward Voltage I _F = 5mA	V _F ^[2]	Green Blue Hyper Red	2.85 2.8 1.95	3.3 3.3 2.3	V
Reverse Current (V _R = 5V)	I _R	Green Blue Hyper Red	-	50 50 10	μА
Temperature Coefficient of λ_{peak} I_F = 5mA, -10°C \leq T \leq 85°C	TC _{λpeak}	Green Blue Hyper Red	0.05 0.04 0.13	-	nm/°C
Temperature Coefficient of λ_{dom} I _F = 5mA, -10°C \leq T \leq 85°C	TC _{λdom}	Green Blue Hyper Red	0.03 0.03 0.06	-	nm/°C
Temperature Coefficient of V_F I_F = 5mA, -10°C \leq T \leq 85°C	TC _V	Green -3 Blue -3 - Hyper Red -1.9		mV/°C	

- 1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ± 1 nm.) 2. Forward voltage: ± 0.1 V.
- Wavelength value is traceable to CIE127-2007 standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value			1114
Parameter		Green	Blue	Hyper Red	Unit
Power Dissipation	P _D [1]	35			mW
Reverse Voltage	V _R	5	5	5	V
Junction Temperature	Tj	115	115	115	°C
Operating Temperature	T _{op}	-40 to +85			°C
Storage Temperature	T _{stg}	-40 to +100			°C
DC Forward Current	I _F ^[2]	10	10	10	mA
Peak Forward Current	I _{FM} ^[3]	50	50	50	mA
Electrostatic Discharge Threshold (HBM)	-	450	250	3000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} [4]	740	690	770	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[4]	650	610	630	°C/W

Notes:

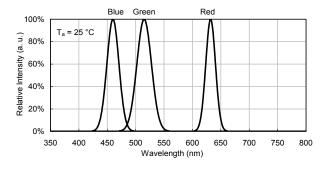
1. Within 35mW when multiple chips are lightened
2. The maximum ratings are valid for the case of lighting a single chip
When two chips are lift at the same time, each chip should be driven at a current lower than 50% of the absolute maximum ratings
When three chips are lift at the same time, each chip should be driven at a current lower than 30% of the absolute maximum ratings
When three chips are lift at the same time, each chip should be driven at a current lower than 30% of the absolute maximum ratings
3. Duty Cycle ≤ 1/20, Pulse Width = 1ms.
4. R_{th. 1.4}, R_{th. 2} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



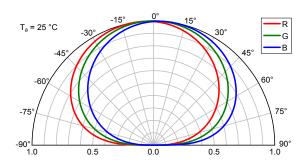


TECHNICAL DATA

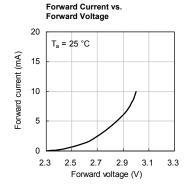
RELATIVE INTENSITY vs. WAVELENGTH

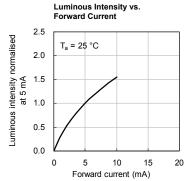


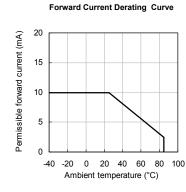
SPATIAL DISTRIBUTION

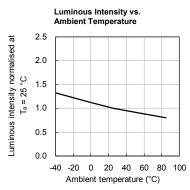


GREEN

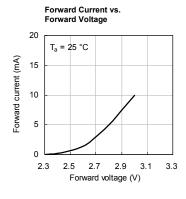


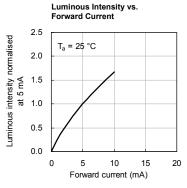


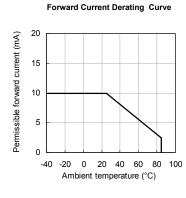


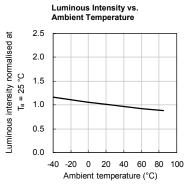


BLUE

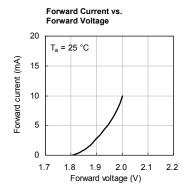


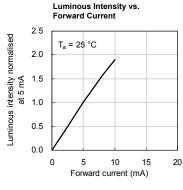


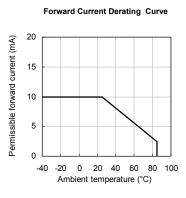


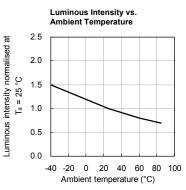


HYPER RED







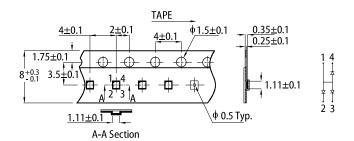




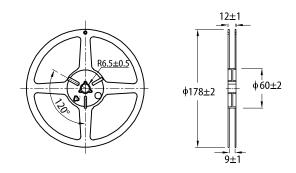
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

300 above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 60~150s 50 . 25℃ 0 50 100 150 200 250 300 (sec) Time

TAPE SPECIFICATIONS (units: mm)

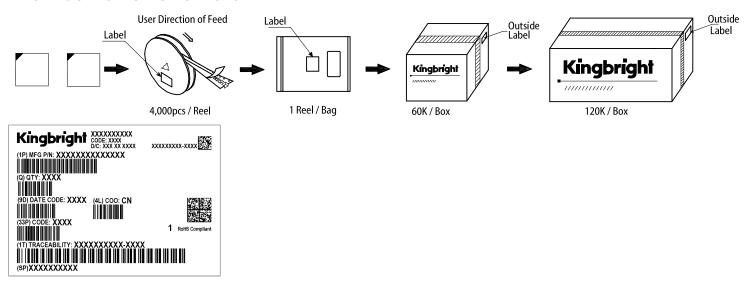


REEL DIMENSION (units: mm)



- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

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